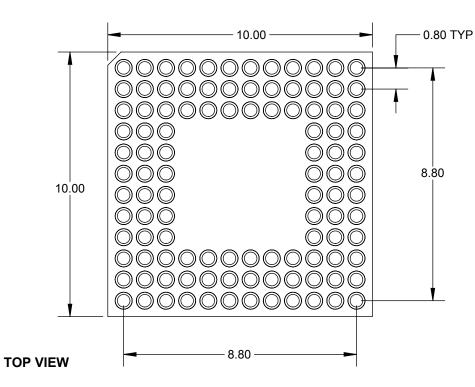
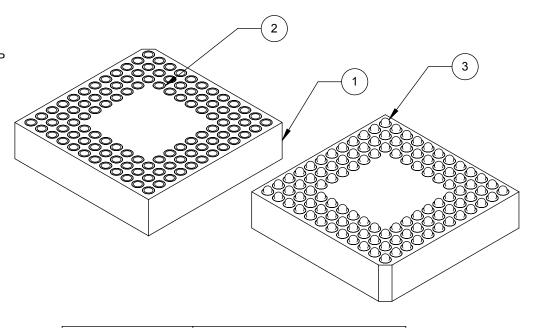
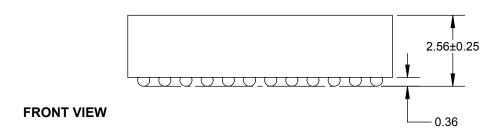
## U.S. Patent No. 8,091,222 B2





ITEM NO.	TEM NO. Description	
1	High Temp Substrate	
2	High Density Giga-Snap Receptacle	
3	Solder Ball, 0.4572mm dia (See Table)	



PART NO. SUFFIX	SOLDER BALL ALLOY		
-64	Sn63Pb37		
-64F*	Sn96.5Ag3.0Cu0.5		
*RoHS Compliant			

## Description: Giga-snaP BGA SMT Foot

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0254mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA108E-B-64 Drawing				
SF-BGA108E-B-64F Drawing	Material: N/A	STATUS: Released	SHEET: 1 OF 2	REV. B
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: N/A Weight: 0.49	ENG: M.A. Fedde	DRAWN BY: D. Hauer	SCALE: 7:1
	Wolgitt. 0.10	FILE: SF-BGA108E-B-64 Dwg	DATE: 06/12/14	

Rev	Date	Initials	Description	
Α	-	-	Original	
В	7/7/15	MT/OA	updated materials to generic definitions	

## Description:

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. Tolerances: Hole diameters  $\pm 0.0254$ mm [ $\pm 0.001$ "], Pitches (from true position)  $\pm 0.0254$ mm [ $\pm 0.001$ "], substrate thickness tolerance  $\pm 10\%$ , all other tolerances  $\pm 0.127$ mm [ $\pm 0.005$ "] unless stated otherwise. Materials and specifications are subject to change without notice.

Specification	Finish: Weight:	STATUS: Released	SHEET: 2 OF 2	REV. B
Ironwood Electronics, Inc. Tele: (800) 404-0204		ENG: M.A. Fedde	DRAWN BY: D. Hauer	SCALE: 7:1
www.ironwoodelectronics.com		FILE: SF-BGA108E-B-64 Dwg	DATE: 06/12/14	